

# 10V Drive Nch MOSFET

## RCJ450N20

### ● Structure

Silicon N-channel MOSFET

### ● Features

- 1) Low on-resistance.
- 2) High-speed switching.
- 3) Wide range of SOA.
- 4) Drive circuits can be simple.
- 5) Parallel use is easy.

### ● Application

Switching

### ● Packaging specifications

| Type      | Package        | Taping |
|-----------|----------------|--------|
|           | Code           | TL     |
|           | Quantity (pcs) | 1000   |
| RCJ450N20 |                | ○      |

### ● Absolute maximum ratings (Ta = 25°C)

| Parameter                      | Symbol        | Limits        | Unit |   |
|--------------------------------|---------------|---------------|------|---|
| Drain-source voltage           | $V_{DSS}$     | 200           | V    |   |
| Gate-source voltage            | $V_{GSS}$     | ±30           | V    |   |
| Drain current                  | Continuous    | $I_D^{*3}$    | ±45  | A |
|                                | Pulsed        | $I_{DP}^{*1}$ | ±180 | A |
| Source current<br>(Body Diode) | Continuous    | $I_S^{*3}$    | 45   | A |
|                                | Pulsed        | $I_{SP}^{*1}$ | 180  | A |
| Avalanche current              | $I_{AS}^{*2}$ | 22.5          | A    |   |
| Avalanche energy               | $E_{AS}^{*2}$ | 160           | mJ   |   |
| Power dissipation              | $P_D^{*4}$    | 211           | W    |   |
| Channel temperature            | $T_{ch}$      | 150           | °C   |   |
| Range of storage temperature   | $T_{stg}$     | -55 to +150   | °C   |   |

\*1  $P_w \leq 10 \mu s$ , Duty cycle  $\leq 1\%$

\*2  $L = 500 \mu H$ ,  $V_{DD} = 50V$ ,  $R_G = 25 \Omega$ ,  $T_{ch} = 25^\circ C$

\*3 Limited only by maximum temperature allowed.

\*4  $T_C = 25^\circ C$

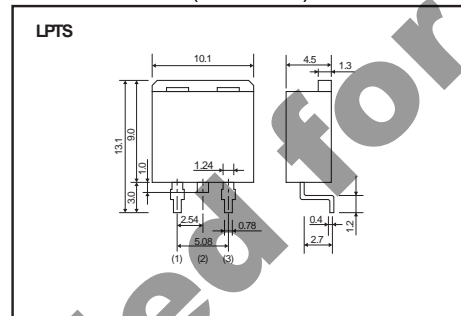
### ● Thermal resistance

| Parameter       | Symbol          | Limits | Unit   |
|-----------------|-----------------|--------|--------|
| Channel to Case | $R_{th(j-c)}^*$ | 0.59   | °C / W |

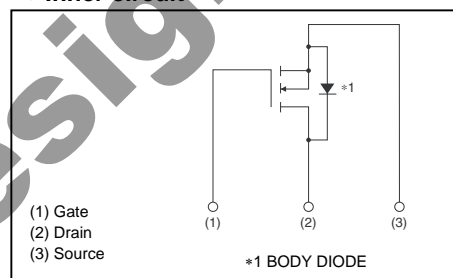
\*  $T_C = 25^\circ C$

\* Limited only by maximum temperature allowed.

### ● Dimensions (Unit : mm)



### ● Inner circuit



(1) Gate  
(2) Drain  
(3) Source

\*1 BODY DIODE

**●Electrical characteristics (Ta = 25°C)**

| Parameter                               | Symbol         | Min. | Typ. | Max. | Unit | Conditions                  |
|---|----------------|------|------|------|------|-----------------------------|
| Gate-source leakage                     | $I_{GSS}$      | -    | -    | ±100 | nA   | $V_{GS}=\pm 30V, V_{DS}=0V$ |
| Drain-source breakdown voltage          | $V_{(BR)DSS}$  | 200  | -    | -    | V    | $I_D=1mA, V_{GS}=0V$        |
| Zero gate voltage drain current         | $I_{DSS}$      | -    | -    | 1    | μA   | $V_{DS}=200V, V_{GS}=0V$    |
| Gate threshold voltage                  | $V_{GS(th)}$   | 3.0  | -    | 5.0  | V    | $V_{DS}=10V, I_D=1mA$       |
| Static drain-source on-state resistance | $R_{DS(on)*}$  | -    | 42   | 55   | mΩ   | $I_D=22.5A, V_{GS}=10V$     |
| Forward transfer admittance             | $ Y_{fs} ^*$   | 17.0 | -    | -    | S    | $V_{DS}=10V, I_D=22.5A$     |
| Input capacitance                       | $C_{iss}$      | -    | 4200 | -    | pF   | $V_{DS}=25V$                |
| Output capacitance                      | $C_{oss}$      | -    | 270  | -    | pF   | $V_{GS}=0V$                 |
| Reverse transfer capacitance            | $C_{rss}$      | -    | 160  | -    | pF   | $f=1MHz$                    |
| Turn-on delay time                      | $t_{d(on)}^*$  | -    | 52   | -    | ns   | $V_{DD}=100V, I_D=22.5A$    |
| Rise time                               | $t_r^*$        | -    | 210  | -    | ns   | $V_{GS}=10V$                |
| Turn-off delay time                     | $t_{d(off)}^*$ | -    | 90   | -    | ns   | $R_L=4.4\Omega$             |
| Fall time                               | $t_f^*$        | -    | 70   | -    | ns   | $R_G=10\Omega$              |
| Total gate charge                       | $Q_g^*$        | -    | 80   | -    | nC   | $V_{DD}=100V, I_D=45A$      |
| Gate-source charge                      | $Q_{gs}^*$     | -    | 28   | -    | nC   | $V_{GS}=10V$                |
| Gate-drain charge                       | $Q_{gd}^*$     | -    | 28   | -    | nC   |                             |

\*Pulsed

**●Body diode characteristics (Source-Drain)**

| Parameter       | Symbol     | Min. | Typ. | Max. | Unit | Conditions           |
|-----------------|------------|------|------|------|------|----------------------|
| Forward Voltage | $V_{SD}^*$ | -    | -    | 1.5  | V    | $I_s=45A, V_{GS}=0V$ |

\*Pulsed

●Electrical characteristic curves (Ta=25°C)

Fig.1 Typical Output Characteristics ( I )

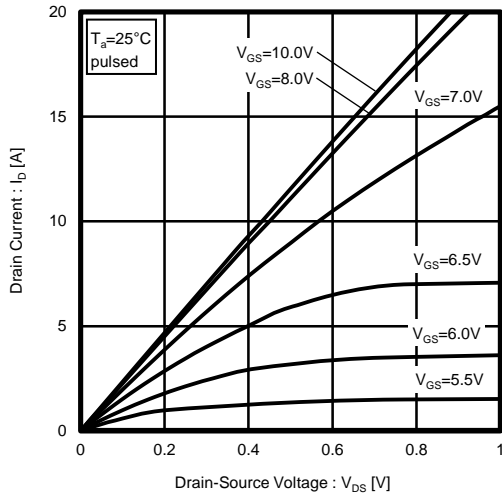


Fig.2 Typical Output Characteristics ( II )

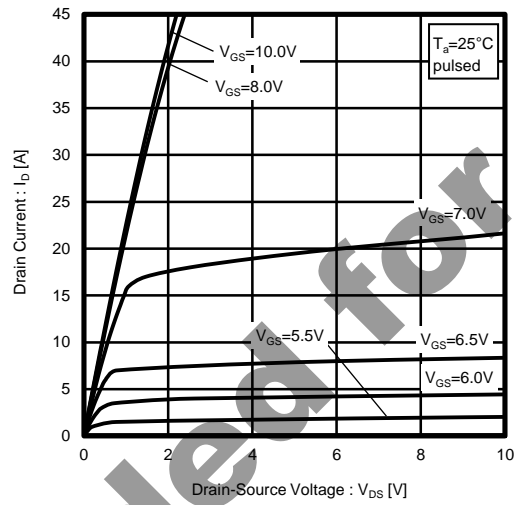


Fig.3 Typical Transfer Characteristics

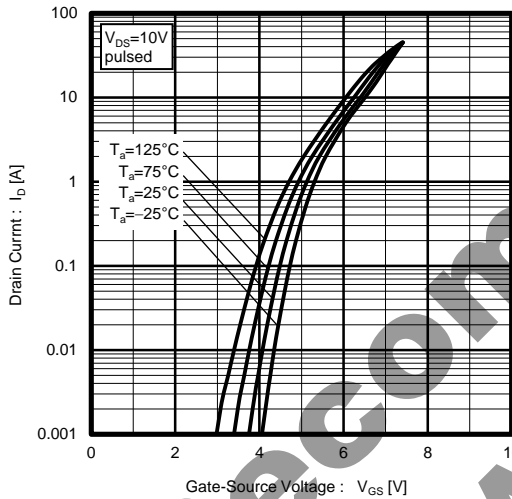


Fig.4 Gate Threshold Voltage vs. Channel Temperature

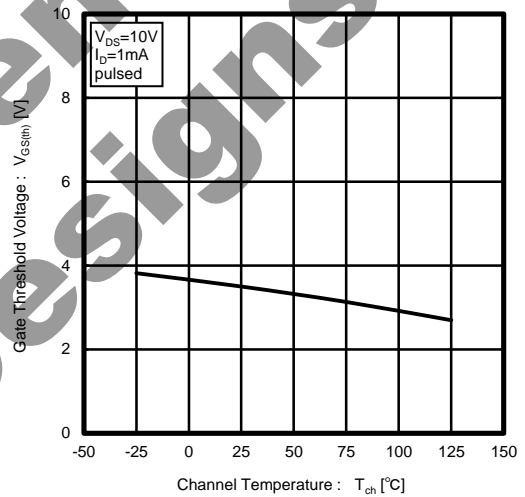


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current

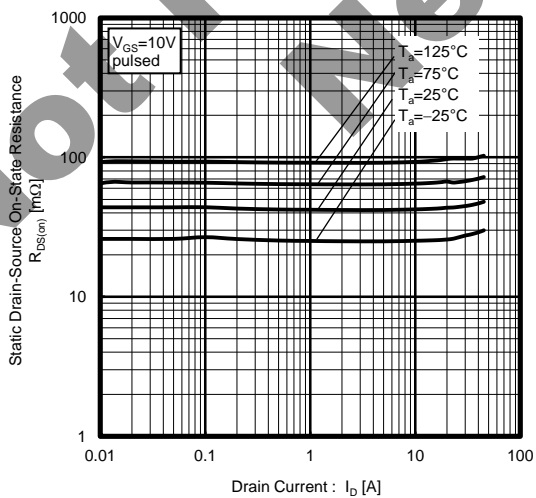


Fig.6 Static Drain-Source On-State Resistance vs. Channel Temperature

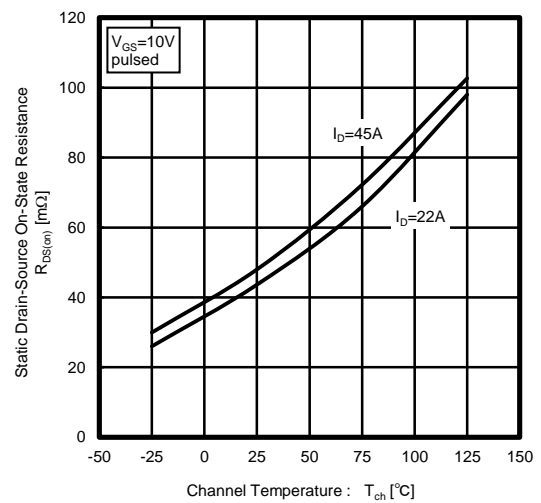


Fig.7 Forward Transfer Admittance vs. Drain Current

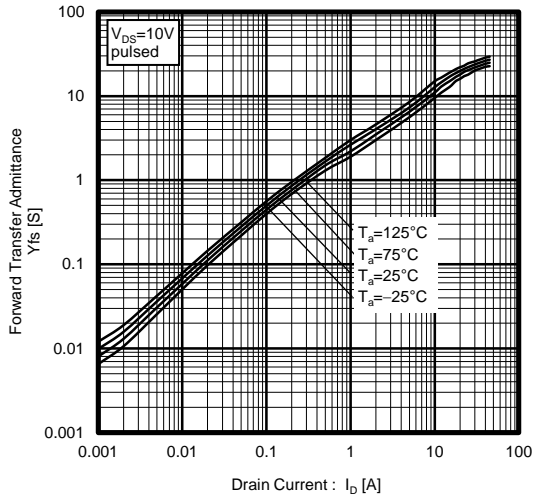


Fig.8 Source Current vs. Source-Drain Voltage

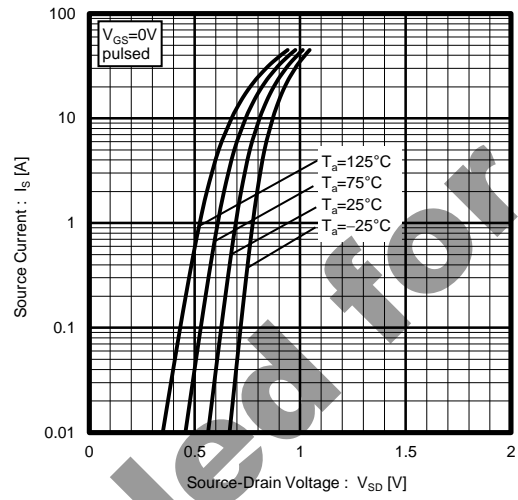


Fig.9 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

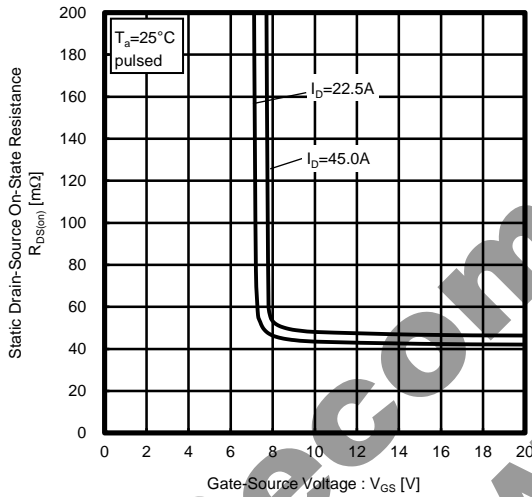


Fig.10 Switching Characteristics

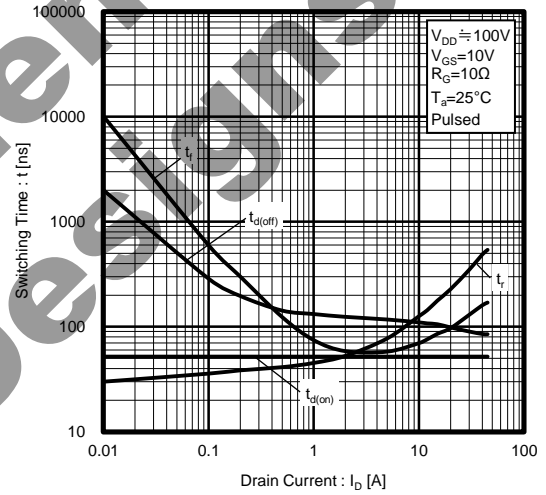


Fig.11 Dynamic Input Characteristics

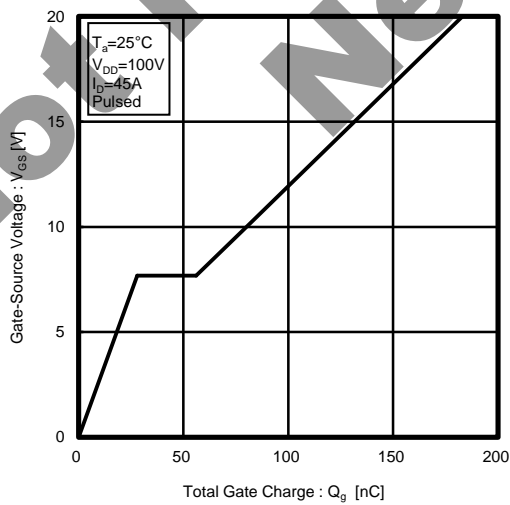


Fig.12 Typical Capacitance vs. Drain-Source Voltage

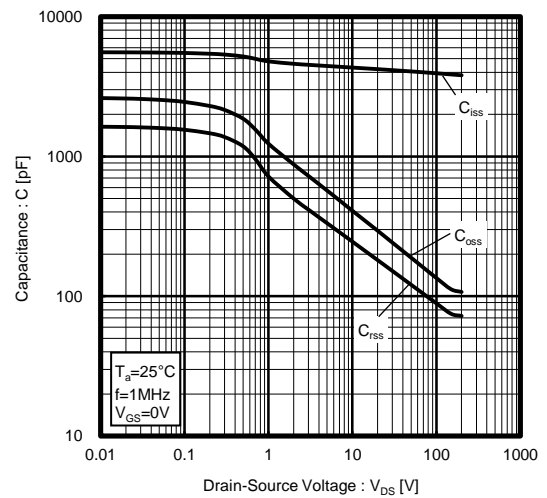


Fig.13 Reverse Recovery Time vs. Source Current

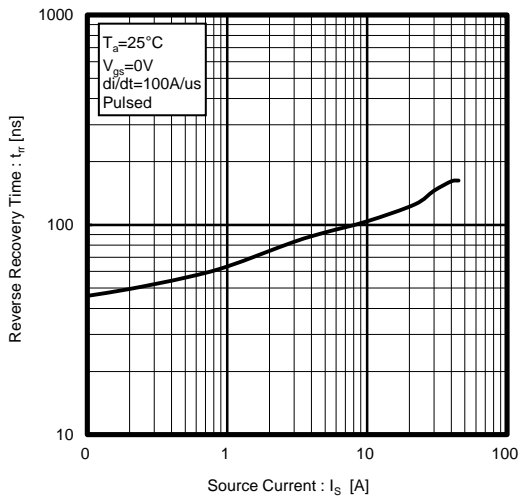


Fig.14 Maximum Safe Operating Area

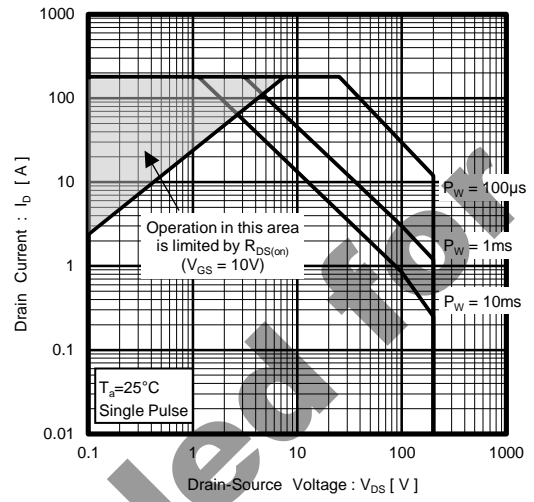
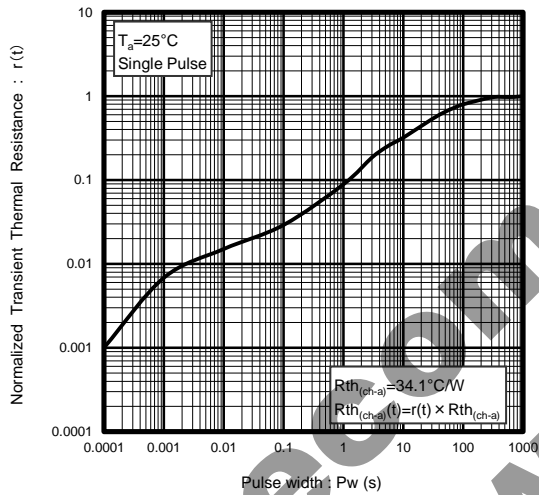


Fig.15 Normalized Transient Thermal Resistance v.s. Pulse Width



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● Measurement circuits

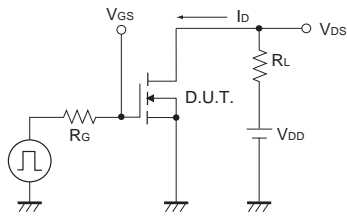


Fig.1-1 Switching Time Measurement Circuit

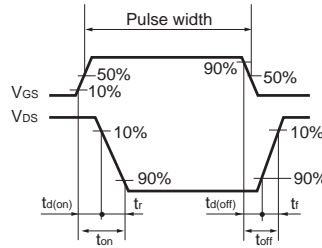


Fig.1-2 Switching Waveforms

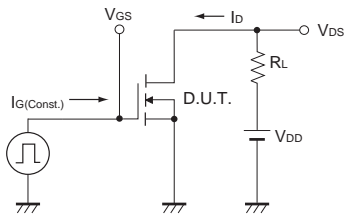


Fig.2-1 Gate Charge Measurement Circuit

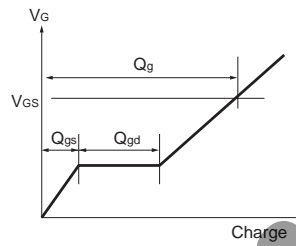


Fig.2-2 Gate Charge Waveform

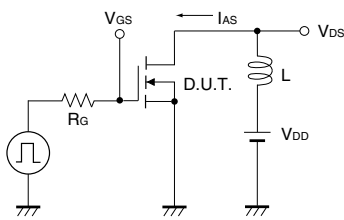


Fig.3-1 Avalanche Measurement Circuit

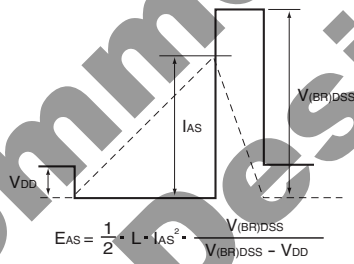


Fig.3-2 Avalanche Waveform

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